Microwave SLCs **ULTRA MAXI Series**



The Ultra Maxi Series is the latest addition to the KYOCERA AVX family of proprietary high k, inter-granular barrier layer dielectic systems. This series is similar to our Maxi & Maxi+ product offerings, but with the notable difference that the dielectric constant has been increased to 60,000 - double the previous high for our industry leading GBBL formulations.

These new Single Layer Ceramic Capacitors, with X7R TCC and rated at 25VDC (-55°C thru +125°C), set a new standard for circuit miniturization. On average, the required board mounting area will be reduced by approximately two-thirds when compared to an equivalent capacitance value for our Maxi+ series. The Ultra Maxi series offers an ideal solution for broadband bypass applications where high performance and the smallest footprint are the primary considerations.

The Ultra Maxi Series is RoHS compliant - as are all KYOCERA AVX SLC products. Terminations (Au over Ti/W) provide an excellent wire bonding surface and are compatible with conductive epoxy and Au/Sn eutectic solder attach.

Samples and custom configurations are available on request.



inches (millimeters)

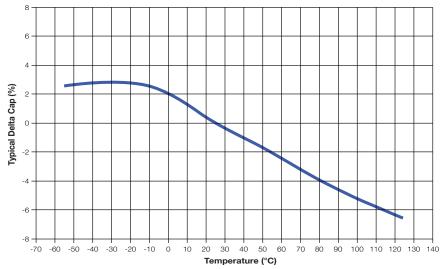
Chulo	Length x Width	Capacitance (pF)		
Style	±.003" (0.076)	Min	Max	
GD10	.010 x .010 (.254 x .254)	200	300	
GD15	.015 x .015 (.381 x .381)	300	600	
GD20	.020 x .020 (.508 x .508)	550	1000	
GD25	.025 x .025 (.635 x .635)	900	1500	
GD30	.030 x .030 (.762 x .762)	1400	2000	
GD35	.035 x .035 (.889 x .889)	1900	2700	
GD40	.040 x .040 (1.016 x 1.016)	2600	3500	
GD45	.045 x .045 (1.143 x 1.143)	3300	4400	
GD50	.050 x .050 (1.270 x 1.270)	4200	5400	
GD55	.055 x .055 (1.397 x1.397)	5100	6500	
Thickness: .0065±.001 (.165±.025)				

Sample kits are available

ULTRA MAXI KIT Catalog # KITSLCK60KSAMPL includes 10 each:

GD1030301ZAW, GD1530601ZAW. GD2030102ZAW, GD3030202ZAW

Capacitance Change with Temperature



HOW TO ORDER





3 Rated Voltage 3 = 25 VDC (k = 60,000)

0 Dielectric 0 = Ultra Maxi

102 Capacitance EIA Cap Code in pF

Ζ

Capacitance Tolerance $M = \pm 20\%$ Z = +80 -20%

Termination Au (100 μ-in) over Ti/W (1000Å)

6N **Packaging**

Antistatic Waffle Pack (400 per)



KYDCER3 | The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.kyocera-avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.

Single Layer Ceramic Capacitors (SLC's)



TABLE I - Dielectric Codes, Types & Product Styles

Dielectr	іс Туре	Dielectric	Temperature Coefficient	Tamparatura Banga	Min Q at 1MHz	Max. DF (%)*		IR (Min) 25°C	
& Code C		Constant	remperature Coernicient	Temperature Range	MIII Q at IMHZ	1 MHz	1 kHz		
	Α	14	+90±30PPM/°C		10,000	0.01	N/A		
NPO	1	31	0±30PPM/°C	-55°C to +125°C	660	0.15	N/A	10 ⁵ Mohms	
	2**	60	0±30PPM/°C		660	0.15	N/A		
	3	130	-750±200PPM/°C		660	0.15	N/A		
	5	165	-1500±500PPM/°C		400	0.25	N/A	10 ⁵ Mohms	
Temp	4	200	±7.5% (non-linear)	FF°C +	400	0.25	N/A		
Comp	7	420	-2000±500PPM/°C	-55°C to +125°C	200	0.70	0.30		
	Υ	650	-4700±1500PPM/°C		400	0.30	0.30		
	6	650	±10% (non-linear)		60	1.50	1.50		
	J	1,100	+5% to -15% (non-linear)		40	2.50	2.00	- 10⁵ Mohms	
	F	2,000	±15% (non-linear)		40	2.50	2.00		
X7R	С	4,000	±15%	-55°C to +125°C	25	4.00***	2.00***		
X/R	G	6,000	+10% to -75% max. change (non-linear)	-55 6 10 +125 6	40	2.50	2.00	TO MONTHS	
	K	9,000	0% to -92% max. change (non-linear)		25	4.00	2.00		
	L	16,000	0/-92%		30	3.50	2.00		
X7S	Z	5,000-18,000	±22%	-55°C to +125°C	30	NA	2.5	10⁴ Mohms	
	8	20,000	±15%						
X7R	9	30,000	±15%	-55°C to +125°C	30	NA	2.5	10⁴ Mohms	
	0	60,000	±15%						

^{*}Capacitance & DF are measured at 1MHz for values \leq 100pF and 1 KHz for capacitance values >100pF

GH SERIES



GB SERIES



GP SERIES



GN SERIES



TABLE II

MIL Reference	Parameter	Method or Paragraph	
MIL-STD-883	Bond Strength	2011.7	
MIL-STD-883	Shear Strength	2019	
MIL-PRF-49464	Thermal Shock	4.8.3	
MIL-PRF-49464	Voltage Conditioning	4.8.3	
MIL-PRF-49464	Temperatue Coefficient	4.8.10	
MIL-STD-202	Low Voltage Humidity	103 A	
MIL-STD-202	Life Test	108	

^{**}NOTE: Code 2 DIELECTRIC IS NOT ROHS COMPLIANT

^{***}DF for the GP, GM, and the GA series with C dielectric is 6.5%

Microwave SLCs **High Reliability Certification Program**





Commercial Off The Shelf

High Reliability Certification Program

The COTS Program provides a cost efficient approach to qualifying standard products for enhanced reliability applications. This flexible program offers standard screening packages with options to support specifics of customer-driven program requirements.

Applications:

· Ruggedized Commercial

(Medical, Industrial, Telecommunications)

Military

(Ground, Naval, Airborne)

· Space/Satellite

HA HB HC HD Ultrasonic Ultrasonic Thermal Shock Thermal Shock HA HA HA HA Standard Standard Standard Standard Certification Certification Certification Certification Package Package Package Package Certification DPA DPA 85/85 85/85 85/85 Solderability Solderability Solderability Wire Bond Wire Bond Wire Bond Certification Certification Life Test Certification

HD

HC

COTS Screening Options

HD: Highest Screening Level

The highest screening option adds life testing as an assurance in mission critical applications and is often used as an alternative in space qualified applications.

HC: Airborne Applications

Often used in airborne applications, this profile closely models the military specifications.

HB: Additional Sample Testing

Built upon our standard HA Screening, this program provides additional sample testing to certify the termination for attachment integrity and the ability to survive and perform in high humidity environments.

HA: Standard Upscreen Package

ATC's Standard Hi Rel certification screening profile is typically used as a lower cost means to certify product reliability. HA screening is used throughout the industry in ground based military applications as well as stringent commercial applications.

P/N Prefix			Evaluation Operation	Sample	
НА	НВ	нс	HD		Size
		х	х	Ultrasonic Screening†	100%
		Х	Х	Thermal Shock (5 Cycles for HC and 20 Cycles for HD)	100%
Х	х	Х	Х	Standard Hi-Rel Certification Package (HA)	100%
		х	Х	Destructive Physical Analysis	see table*
	х	х	Х	85/85 (Low Voltage Moisture Humidity)	13 units*
	х	х	Х	Solderability (Solderable or Solder Coated Only)	5 units*
	х	х	Х	Wire Bond Test (Gold Terminated Chips Only)	13 units*
			Х	Life Test (2000)	25 units*

DPA Sample Table			
Lot Size	Sample		
1 - 500	14		
501 - 10,000	32		
10,001 - 35,000	50		
35,001 and up	80		

[†] Ultrasonic Screening does not apply to SLC products



^{*} Additional sample units required that have passed the 100% testing along with the deliverable (flight) quantity